

# FS6M07652RTC

## Fairchild Power Switch(FPS)

### Features

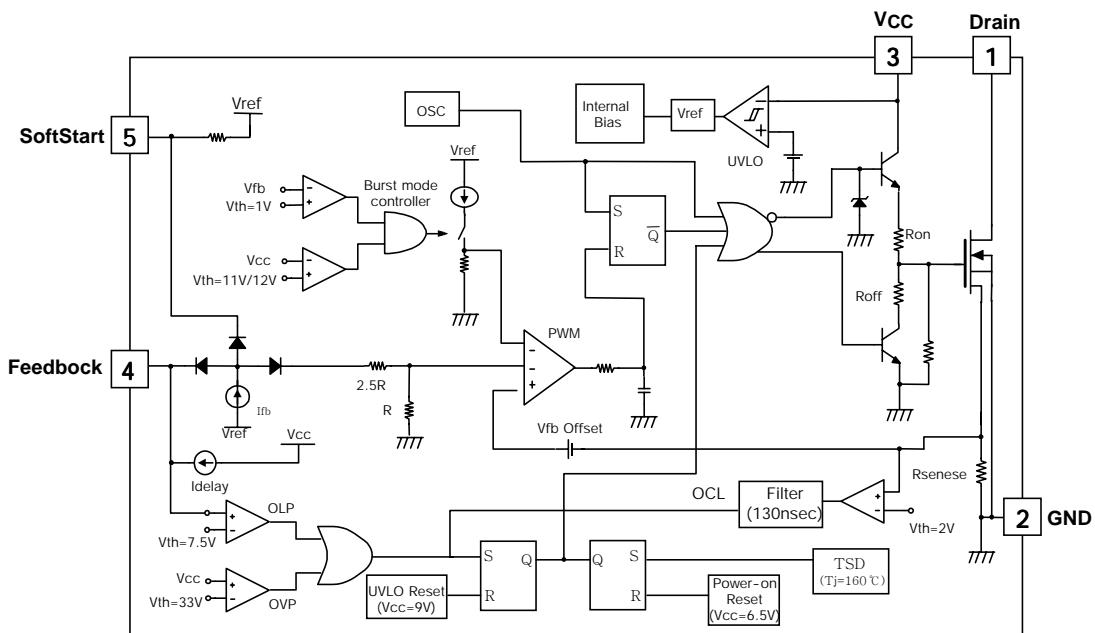
- Fixed Frequency
- Internal Burst Mode Controller for Stand-by Mode
- Pulse By Pulse Over Current Limiting
- Over Current Protection(Auto Restart Mode)
- Over Voltage Protection (Auto Restart Mode)
- Over Load Protection(Auto Restart Mode)
- Internal Thermal Shutdown Function(Latch Mode)
- Under Voltage Lockout
- Internal High Voltage Sense FET
- Soft Start

### Description

The Fairchild Power Switch(FPS) product family is specially designed for an off line SMPS with minimal external components. The Fairchild Power Switch(FPS) consist of high voltage power SenseFET and current mode PWM IC. Included PWM controller features integrated fixed oscillator, under voltage lock out, leading edge blanking, optimized gate turn-on/turn-off driver, thermal shut down protection, over voltage protection, and temperature compensated precision current sources for loop compensation and fault protection circuitry. compared to discrete MOSFET and controller or RCC switching converter solution, a Fairchild Power Switch(FPS) can reduce total component count, design size, and weight and at the same time increase efficiency, productivity, and system reliability. It has a basic platform well suited for cost effective LCD monitor power supply.



### Internal Block Diagram



## Absolute Maximum Ratings

(Ta=25°C, unless otherwise specified)

Characteristic	Symbol	Value	Unit
Maximum Drain Voltage	V <sub>D, MAX</sub>	650	V
Drain-Gate Voltage (R <sub>GS</sub> =1MΩ)	V <sub>DGR</sub>	650	V
Gate-Source (GND) Voltage	V <sub>GS</sub>	±30	V
Drain Current Pulsed <sup>(1)</sup>	I <sub>DM</sub>	14.4	ADC
Continuous Drain Current (T <sub>c</sub> = 25°C)	I <sub>D</sub>	3.6	ADC
Continuous Drain Current (T <sub>C</sub> =100°C)	I <sub>D</sub>	2.28	ADC
Single Pulsed Avalanche Current <sup>(3)</sup> (Energy <sup>(2)</sup> )	I <sub>AS(EAS)</sub>	17(570)	A(mJ)
Maximum Supply Voltage	V <sub>CC, MAX</sub>	35	V
Input Voltage Range	V <sub>FB</sub>	-0.3 to V <sub>CC</sub>	V
	V <sub>SS</sub>	-0.3 to 10	V
Total Power Dissipation	P <sub>D</sub> (Watt H/S)	46	W
	Darting	0.37	W/°C
Operating Junction Temperature	T <sub>j</sub>	+150	°C
Operating Ambient Temperature	T <sub>A</sub>	-25 to +85	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

**Notes:**

1. Repetitive rating: Pulse width limited by maximum junction temperature
2. L=81mH, starting T<sub>j</sub>=25°C
3. L=13uH, starting T<sub>j</sub>=25°C

## Electrical Characteristics (SFET part)

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BVDSS	VGS=0V, ID=250µA	650	-	-	V
Zero Gate Voltage Drain Current	IDSS	VDS=650V, VGS=0V	-	-	200	µA
		VDS=520V VGS=0V, TC=125°C	-	-	300	µA
Static Drain-source On Resistance <sup>(1)</sup>	RDS(ON)	VGS=10V, ID=1.8A	-	1.3	1.6	Ω
Forward Trans Conductance <sup>(2)</sup>	gfs	VDS=50V, ID=1.8A	-	3.3	-	S
Input Capacitance	Ciss	VGS=0V, VDS=25V, f = 1MHz	-	1200	-	pF
Output Capacitance	Coss		-	125	-	
Reverse Transfer Capacitance	Crss		-	23	-	
Turn On Delay Time	td(on)	VDD=325V, ID=6.5A (MOSFET switching time are essentially independent of operating temperature)	-	22	-	nS
Rise Time	tr		-	70	-	
Turn Off Delay Time	td(off)		-	105	-	
Fall Time	tf		-	65	-	
Total Gate Charge (Gate-Source+Gate-Drain)	Qg	VGS=10V, ID=6.5A, VDS=520V (MOSFET Switching time are Essentially independent of Operating temperature)	-	40	-	nC
Gate Source Charge	Qgs		-	6.5	-	
Gate Drain (Miller) Charge	Qgd		-	18	-	

**Note:**

1. Pulse test : Pulse width ≤ 300µS, duty 2%

$$2. S = \frac{1}{R}$$

**Electrical Characteristics** (Continued)

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
<b>UVLO SECTION</b>						
Start Threshold Voltage	VSTART	VFB = GND	14	15	16	V
Stop Threshold Voltage	VSTOP	VFB = GND	8	9	10	V
<b>OSCILLATOR SECTION</b>						
Initial Frequency	FOSC	-	63	70	77	kHz
Voltage Stability	FSTABLE	12V ≤ VCC ≤ 23V	0	1	3	%
Temperature Stability (2)	ΔFOSC	-25°C ≤ Ta ≤ 85°C	0	±5	±10	%
Maximum Duty Cycle	DMAX	-	75	80	85	%
Minimum Duty Cycle	DMIN	-	-	-	0	%
<b>FEEDBACK SECTION</b>						
Feedback Source Current	I <sub>FB</sub>	VFB = GND	0.7	0.9	1.1	mA
Shutdown Feedback Voltage	V <sub>SD</sub>	VFB ≥ 6.9V	6.9	7.5	8.1	V
Shutdown Delay Current	I <sub>DELAY</sub>	VFB = 5V	3.2	4.0	4.8	μA
<b>SOFTSTART SECTION</b>						
Softstart Voltage	V <sub>SS</sub>	VFB = 2	4.7	5.0	5.3	V
Softstart Current	I <sub>SS</sub>	V <sub>SS</sub> = V	0.8	1.0	1.2	mA
<b>BURST MODE SECTION</b>						
Burst Mode Low Threshold Voltage	V <sub>BURL</sub>	VFB = 0V	10.4	11.0	11.6	V
Burst Mode High Threshold Voltage	V <sub>BURH</sub>	VFB = 0V	11.4	12.0	12.6	V
Burst Mode Enable Feedback Voltage	V <sub>BEN</sub>	VCC = 10.5V	0.7	1.0	1.3	V
Burst Mode Peak Current Limit (4)	I <sub>BURPK</sub>	VCC = 10.5V, VFB = 0V	0.38	0.5	0.62	A
Burst Mode Frequency	F <sub>BUR</sub>	VCC = 10.5V, VFB = 0V	63	70	77	KHz
<b>CURRENT LIMIT(SELF-PROTECTION)SECTION</b>						
Peak Current Limit (4)	I <sub>OVER</sub>	-	1.76	2.0	2.24	A
<b>PROTECTION SECTION</b>						
Over Voltage Protection	V <sub>OVP</sub>	VCC ≥ 29V	29	33	37	V
Over Current Latch Voltage (3)	V <sub>OCL</sub>	-	1.8	2.0	2.2	V
Thermal Shutdown Temp (2)	T <sub>SD</sub>	-	140	160	-	°C
<b>TOTAL DEVICE SECTION</b>						
Start Up Current	I <sub>START</sub>	VFB = GND, VCC = 14V	-	0.1	0.17	mA
Operating Supply Current (1)	I <sub>OP</sub>	VFB = GND, VCC = 16V	-	10	15	mA
	I <sub>OP(MIN)</sub>	VFB = GND, VCC = 12V				
	I <sub>OP(MAX)</sub>	VFB = GND, VCC = 30V				

**Notes:**

1. These parameters are the current flowing in the Control IC.
2. These parameters, although guaranteed at the design, are not 100% tested in production.
3. These parameters, although guaranteed, are tested in EDS(wafer test) process.
4. These parameters indicate Inductor current.

## Typical Performance Characteristics

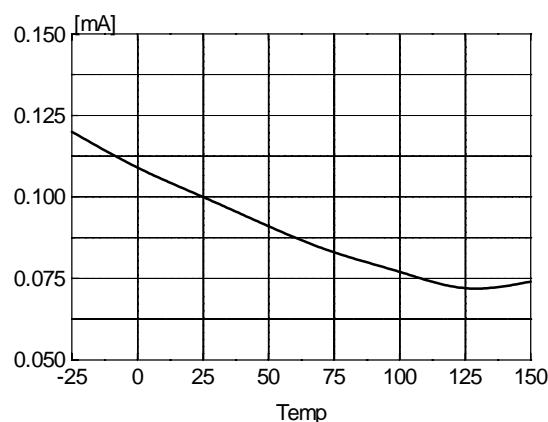


Figure 1. Start Up Current vs. Temp

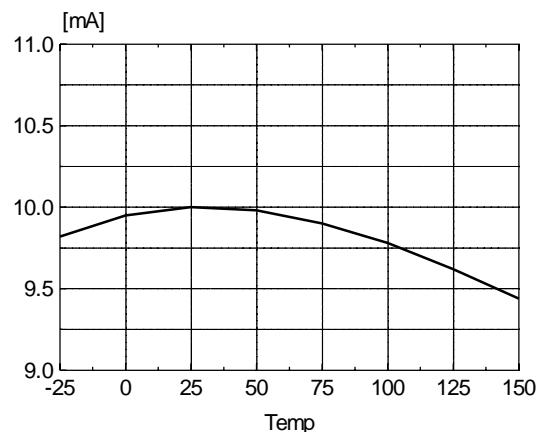


Figure 2. Operating Current vs. Temp

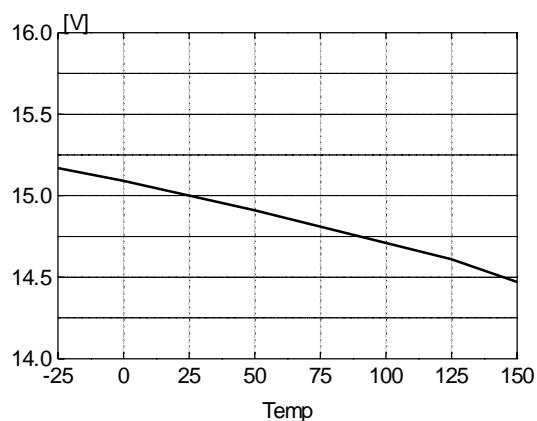


Figure 3. Start Threshold Voltage vs. Temp

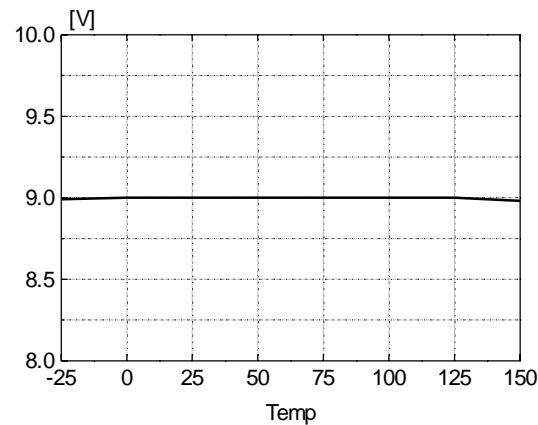


Figure 4. Stop Threshold Voltage vs. Temp

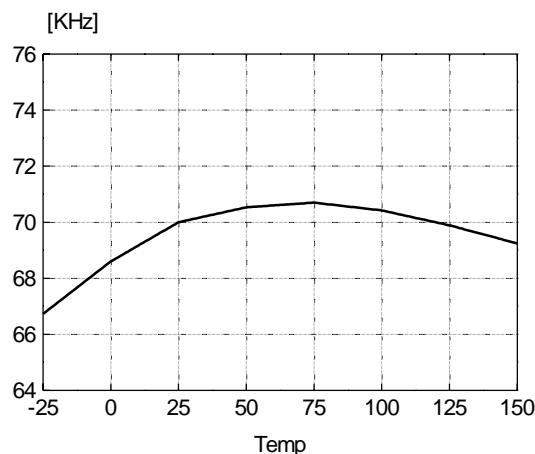


Figure 5. Initial Frequency vs. Temp

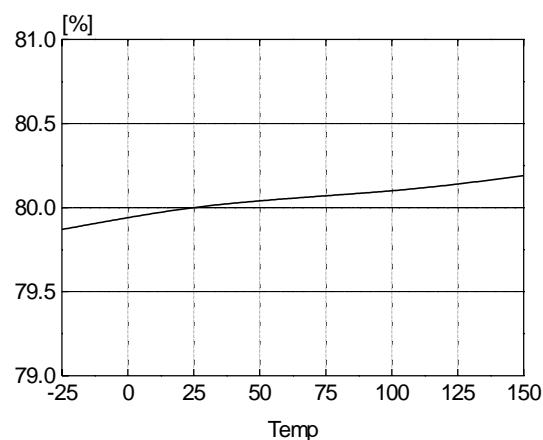


Figure 6. Maximum Duty vs. Temp

## Typical Performance Characteristics (Continued)

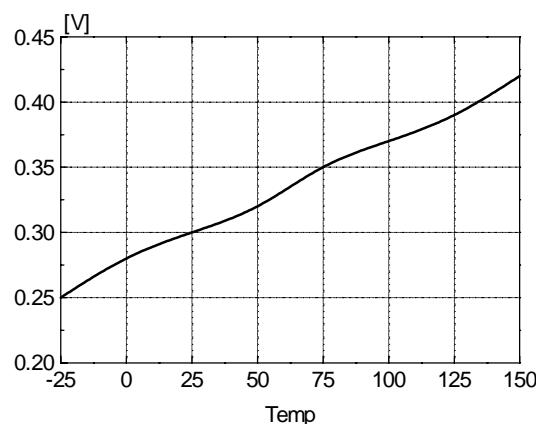


Figure 7. Feedback Offset Voltage vs. Temp

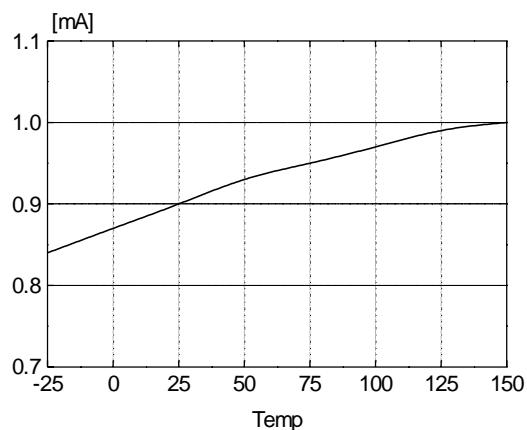


Figure 8. Feedback Source Current vs. Temp

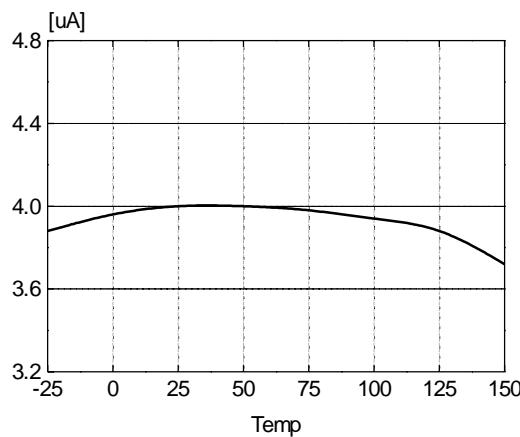


Figure 9. ShutDown Delay Current vs. Temp

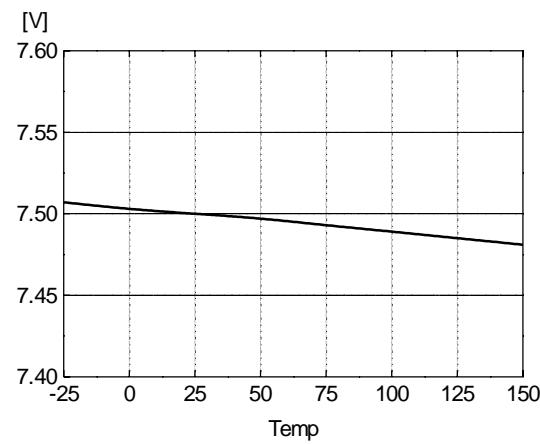


Figure 10. ShutDown Feedback Voltage vs. Temp

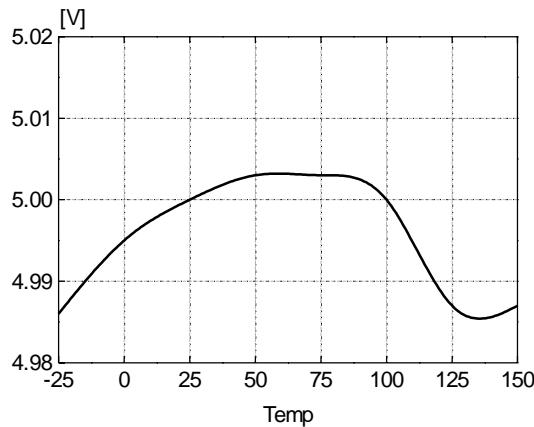


Figure 11. Softstart Voltage vs. Temp

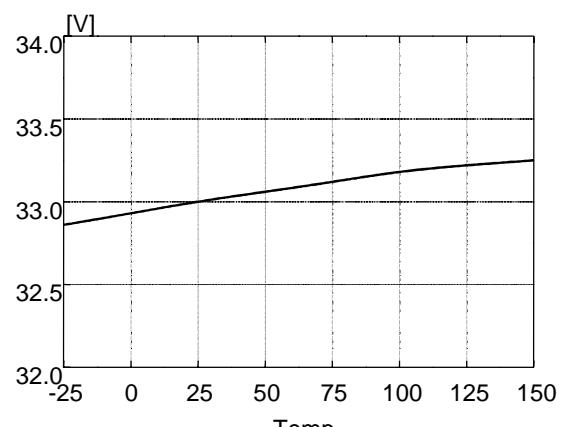


Figure 12. Over Voltage Protection vs. Temp

## Typical Performance Characteristics (Continued)

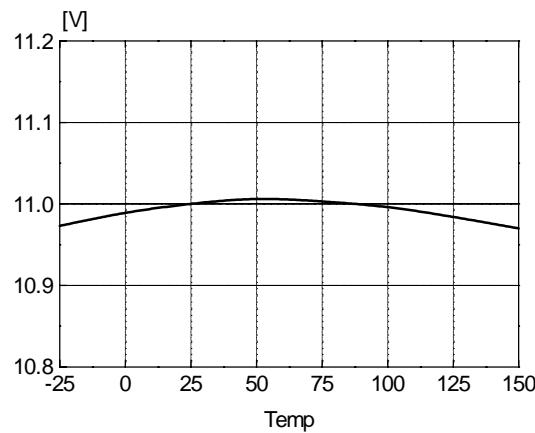


Figure 13. Burst Mode Low Voltage vs. Temp

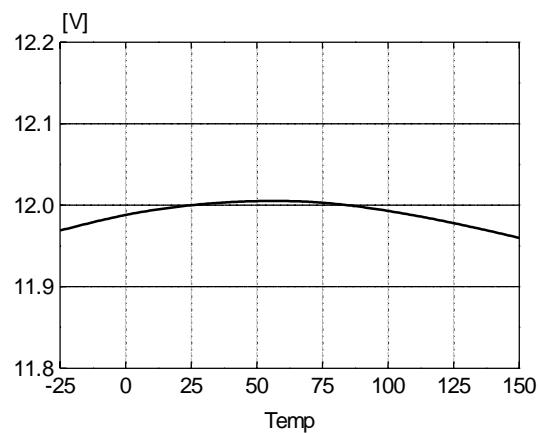


Figure 14. Burst Mode High Voltage vs. Temp

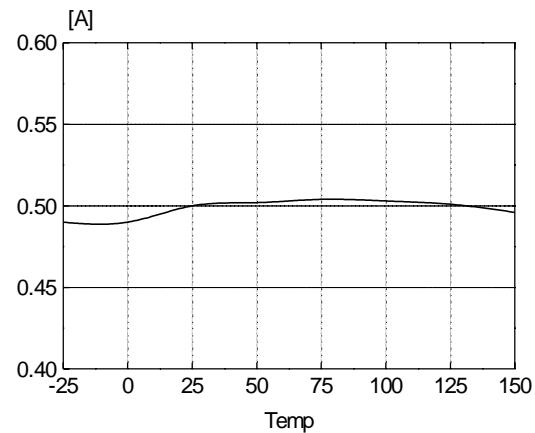


Figure 15. Burst Mode Peak Current vs. Temp

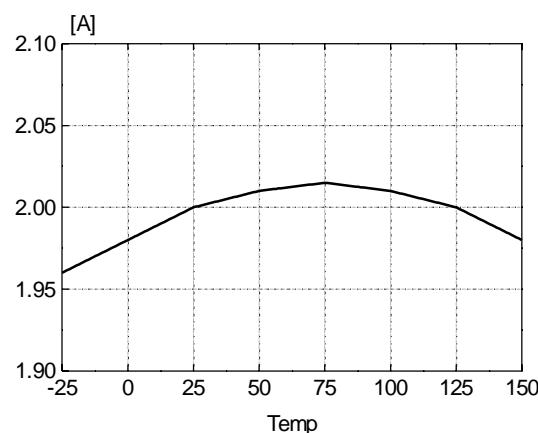
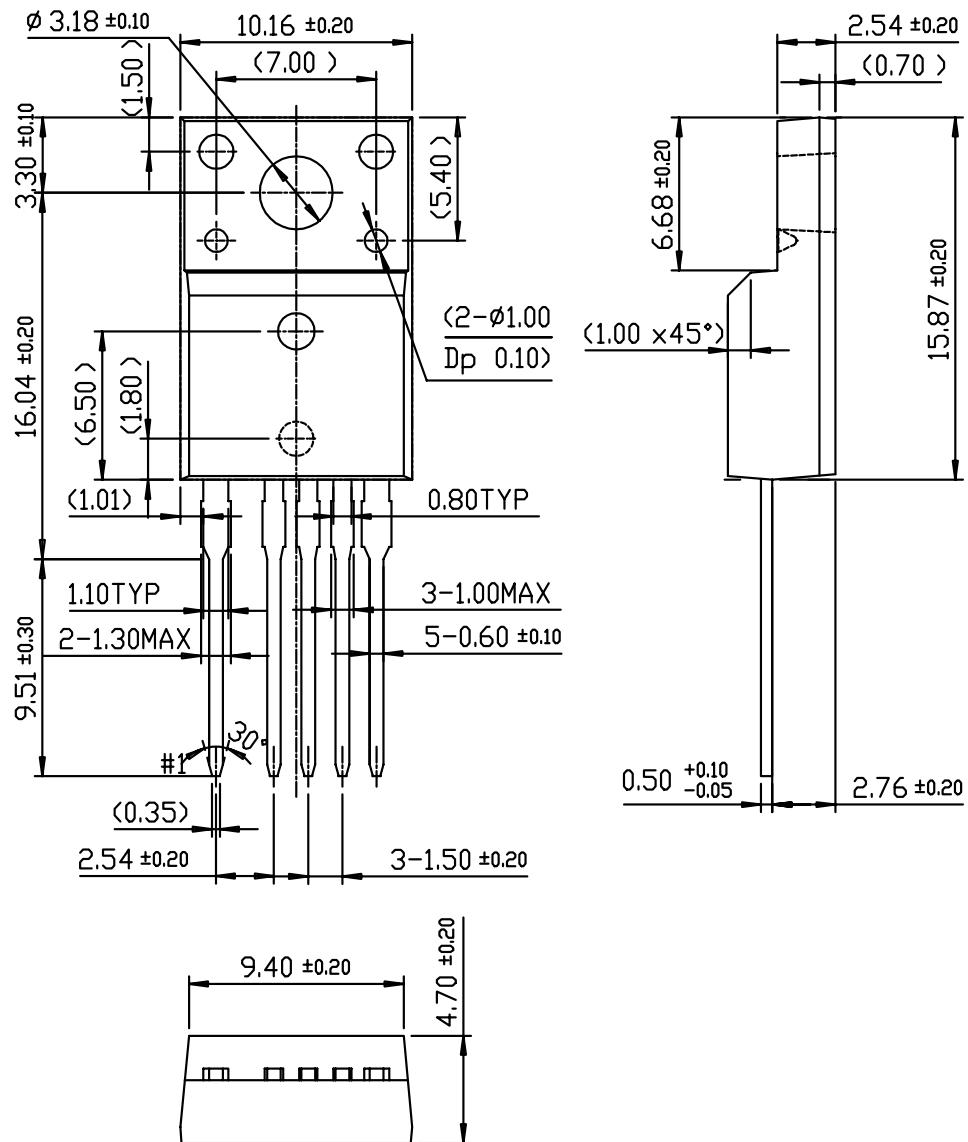


Figure 16. Over Current Limit vs. Temp

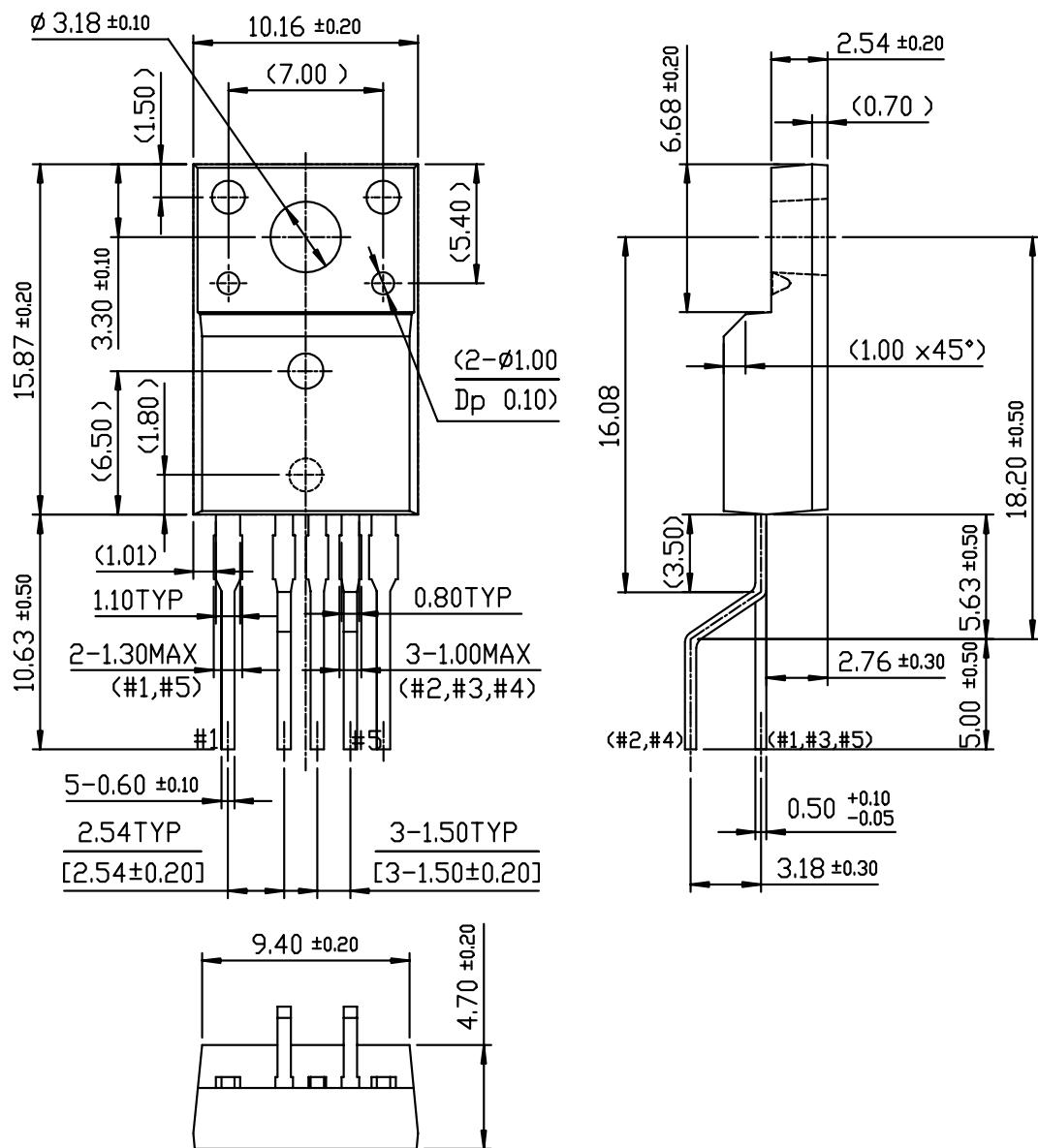
## Package Dimensions

**TO-220F-5L**



## Package Dimensions (Continued)

### TO-220F-5L(Forming)



## Ordering Information

Product Number	Package	Marking Code	BVdss	Rds(on)
FS6M07652RTC-TU	TO-220F-5L	6M07652R C	650V	1.3
FS6M07652RTC-YDT	TO-220F-5L(Forming)			

TU : Non Forming Type

YDT : Forming Type

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